



8. IMPEDANCE CONTROL TO 50 OHMS FOR 5 MIL TRACES. 100 OHM DIFFERENTIAL +/-10%; 5.1 MIL TRACE EXTERNAL.
7. SURFACE FINISH SHALL BE IMMERSION GOLD.
6. FINISHED BOARD SHALL BE FREE OF BURRS ON EDGES.
5. PLATED THRU HOLE SIZE TOLERANCES SHALL BE +/- .003 INCH. UNPLATED THRU HOLE SIZE TOLERANCES SHALL BE +/- .002 INCH.
4. SOLDERMASK ON BOTH SIDES OF THE BOARD SHALL BE S.M.O.B.C., LPI, COLOR BLACK, MATTE.
3. MINIMUM TRACE AND SPACE SHALL BE .005 OF AN INCH.
2. COPPER PLATED SURFACE CONDUCTORS SHALL BE THE EQUIVALENT OF 1 OZ. COPPER AFTER PLATING. PLANE LAYERS SHALL BE 1 OZ. COPPER. AVERAGE COPPER ON THE WALL OF THE PLATED HOLE SHALL BE .001 INCH.
1. TOTAL BOARD THICKNESS SHALL BE .062 +/- .007 INCHES. ALL MATERIAL SHALL BE NEMA GRADE FR-4 OR EQUIVALENT. (Tg>+170 DEG. C)

NOTES: UNLESS OTHERWISE SPECIFIED

MILL CODES	
1	1.000
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49	49.000
50	50.000

DATE	REVISION	DESCRIPTION
7-21-15 <td>1 <td>INITIAL ASSEMBLY </td></td>	1 <td>INITIAL ASSEMBLY </td>	INITIAL ASSEMBLY

REVISED	BY	DATE	REASON

DATE	7-21-15	REVISION	1
PROJECT	OSD 10800 TOUCH DISPLAY I/F BOARD		
SCALE	SHEET 1 OF 1		
DATE	7-21-15	REVISION	1
PROJECT	OSD 10800 TOUCH DISPLAY I/F BOARD		
SCALE	SHEET 1 OF 1		

FABRICATION DRAWING
 OSD 10800 TOUCH DISPLAY I/F BOARD
 SHEET 1 OF 1
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